

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
DINESH KUMAR	09/25/2019
VINAYAK JADHAV	09/25/2019
SHASHANK MOHAN JAIN	09/25/2019
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State/Country:	GERMANY
Postal Code:	69190
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	18205873
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NAME OF SUBMITTER:	JAMES M. WAKELY
SIGNATURE:	/James Wakely/
DATE SIGNED:	06/06/2023
Total Attachments: 3	
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source=190213US01_S23289_Assignments#page3.tif	

Attorney Dkt. No. S23.289 / 190213US01

ASSIGNMENT

For valuable consideration, I, Dinesh Kumar,
hereby assign to

SAP SE, a corporation of Europe having a place of business at Dietmar-Hopp-Allee 16, 69190 Walldorf,
Germany

and its successors, and assigns (collectively, the ASSIGNEE) my entire right, title and interest throughout the world in the inventions and improvements in a patent document entitled:

DYNAMIC, DISTRIBUTED, AND SCALABLE SINGLE ENDPOINT SOLUTION FOR A SERVICE IN CLOUD PLATFORM

which is found in the:

US patent application filed on: October 21, 2019

under Application No. 16/658,382

I authorize and request the attorneys of record or the attorney filing the application to insert into this assignment the filing date and serial number of the application when known. This assignment includes the foregoing patent application or patent, as well as continuations and divisionals of said application, all legal equivalents in any country, and all patents issuing from such legal equivalents; all patents, utility models, and design registrations granted by any jurisdiction for any of said inventions and improvements; and the right to claim priority based on the filing date of the foregoing patent application or patent under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes. I authorize the Assignee to apply in all countries in my name or in its own name for patents, utility models, and design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements. I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into that would conflict with this assignment. I hereby state and agree that no assignment, sale, agreement, or encumbrance has been or will be made or entered into that would conflict with this assignment. I further agree for myself and my heirs, legal representatives, and assigns to provide to the Assignee promptly upon its request and at its expense all pertinent facts and documents relating to any of said inventions and improvements or said patents and legal equivalents as may be known and accessible to me and to testify as to the same in any interference, litigation, or proceeding relating thereto; and I agree promptly to perform such lawful acts and to sign such further applications, assignments, statements, and other lawful documents as the Assignee may reasonably request to effectuate fully this assignment.

Inventor's Signature:

DocuSigned by:
Dinesh Kumar
CFDE01F3218045B...

9/25/2019

Dinesh Kumar

Attorney Dkt. No. S23.289 / 190213US01

ASSIGNMENT

For valuable consideration, I, Vinayak Jadhav,

hereby assign to

SAP SE, a corporation of Europe having a place of business at Dietmar-Hopp-Allee 16, 69190 Walldorf, Germany

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Inventor's Signature:

DocuSigned by:
Vinayak Jadhav
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9/25/2019

Vinayak Jadhav

Attorney Dkt. No. S23.289 / 190213US01

ASSIGNMENT

For valuable consideration, I, Shashank Mohan Jain,

hereby assign to

SAP SE, a corporation of Europe having a place of business at Dietmar-Hopp-Allee 16, 69190 Walldorf, Germany

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Inventor's Signature:

DocuSigned by:
Shashank Mohan Jain
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9/25/2019

Shashank Mohan Jain

PATENT